Assembly and rework at IPC/ APEX EXPO 2011

ECN Europe

The OK International team will display and demonstrate its full range of soldering and production assembly technologies at this years IPC/APEX Expo in Las Vegas, April 12-14. These industry-leading solutions will be fully operational at booth # 1634, including advanced soldering, desoldering and rework systems, programmable pre-heaters, fume extraction and a comprehensive range of dispensing technologies.

OK International is not simply a hardware provider, explained Mark Cowell, President and CEO, We are a process enabler with a proven commitment to reducing our customers training investment, extending their application capabilities and measurably enhancing productivity.

The sophisticated APR-5000-XLS Array Package Rework System is just one example of a product delivering those advantages. This advanced platform enables the simultaneous use of inner and outer preheaters which increase the productivity of the unit by reducing rework cycle time. A lowered nozzle temperature protects components under rework to achieve the same required temperature with solder joints or balls and reducing BGA lid temperatures a major advantage for todays production professionals.

Also on display at booth #1634 will be the MRS-1000 Modular Rework System. It is an integrated convection rework system for the removal and placement of BGA/CSP and SMT components. The MRS-1000 will be shown alongside the companys popular MFR-1100 Series Soldering System, featuring SmartHeat® technology, uniquely available from OK International. Designed for flexibility as well as performance, the MFR-1100 Series raises power output without increasing tip temperature, and a tweezer handpiece readily transforms the system into a highly effective rework tool.

OK International will also feature the Metcal MX-5000 Soldering, Desoldering and Rework System. A high performance system for complex assembly challenges, the MX-5000 combines increased power with the companys exclusive SmartHeat® Technology to eliminate the risk of overshoot while delivering high productivity soldering and rework, particularly on high thermal mass assemblies and advanced packages. The MX-5000 also incorporates an integral digital power indication display for continuous operator feedback and consistent, quality solder joints. Visit OK International Booth #1634 at IPC/APEX to see these technologies in action.

[1]

SOURCE [2]

Source URL (retrieved on *03/09/2014 - 9:41pm*):
http://www.ecnmag.com/blogs/2011/03/assembly-and-rework-ipc/apex-expo-2011

Links:
[1] http://ecneurope.files.wordpress.com/2011/03/oki.jpg
[2] http://ecneurope.wordpress.com/2011/03/28/assembly-and-rework-at-ipc-apex-expo-2011/